

LINEAR TECHNOLOGY MATERIALS DECLARATION

LTC3866EFE#TRPBF

(Engineering Calculation)

TSSOP Exp. Pad

(printed on: 2014-01-20 02:42:11)

TOTAL MASS (g): 0.093552

COMPONENT MATERIAL	VENDOR/INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL Pkg.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.002180	1000000	23302.462896		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.030596	975000	32704.8125		
		Iron (Fe)	7439-89-6	0.000753	24000	8048.96923828		
		Phosphorus (P)	7723-14-0	0.000009	300	96.2028198242		
		Zinc (Zn)	7440-66-6	0.000022	700	235.162460327		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-99-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		<b>Lead Frame Total:</b>				<b>0.031380</b>	<b>1000000</b>	<b>335427.1875</b>
		Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0
Exter. Plating Sn	7440-31-5			0.002480	1000000	26513.0039062		
<b>External Plating Total:</b>						<b>0.002480</b>	<b>1000000</b>	<b>26513.0039062</b>
Inter. Plating Ni	7440-02-0			0.000000	0	0		
Inter. Plating Ag	7440-22-4			0.000066	1000000	8615.49707031		
<b>Internal Plating Total:</b>						<b>0.000066</b>	<b>1000000</b>	<b>8615.49707031</b>
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000727	750000	7771.05029297		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000242	250000	2586.78686523		
		<b>Die Attach Total:</b>				<b>0.000969</b>	<b>1000000</b>	<b>10357.8369144</b>
		Encapsulation	MULTIAROMATIC RESIN BOND FREE	Resin (EP)		0.007460	135000	79741.4453125
Bromine (Br)	40093-93-8			0.000000	0	0		
Silica (SiO2)	60676-86-0			0.047524	860000	507993.625		
Antimony Trioxide (Sb2O3)	1309-64-4			0.000000	0	0		
Metal Hydroxide				0.000000	0	0		
Carbon Black (C)	1333-86-4			0.000276	5000	2950.2199707		
<b>Encapsulation Total:</b>						<b>0.055260</b>	<b>1000000</b>	<b>590685.3125</b>
Bond Wire Estimated	AFW/TANAKA/Kn	Gold (Au)	7440-57-5	0.000477	1000000	5098.74951172		

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